

In the claims:

Please amend claims 18 and 22. The status of the claims is as follows:

1. (Previously Presented) A cooling structure of an electronic equipment needing forced-air-cooling comprising:

at least one substrate housing part detachably housing therein one or plurality of substrate units;

an upstream side duct provided at the upstream side of air for cooling which is allowed to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling which passed from said upstream side duct through said substrate housing part to flow;

exhaust means provided at an exhaust part for allowing said downstream side duct to open to an outside air to forcibly discharge air in said substrate housing part to the outside air, thereby allowing the air for cooling to flow to said substrate housing part; and

air adjusting means for adjusting the air for cooling which passes from said upstream side duct to said downstream side duct through said substrate housing part, said air adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part,

wherein said air adjusting means is installed in either or both of a first boundary part where said substrate housing part and said downstream side duct contact each other or a second boundary part where said substrate housing part and said upstream side

duct contact each other, thereby adjusting the air for cooling to a volume of air corresponding to said substrate units installed in said substrate housing part.

2. (Previously Presented) A cooling structure of an electronic equipment according to Claim 1, wherein said air adjusting means adjusts a volume of entire air for cooling which flows to said substrate housing part.

3. (Original) A cooling structure of an electronic equipment according to Claim 1, wherein said air adjusting means changes exhaust capacity of the exhaust means.

4. (Previously Presented) A cooling structure of an electronic equipment according to Claim 1, further comprising first and second substrate housing frame bodies which are detachably provided in a housing, and said substrate housing part is installed in each of said substrate housing frame bodies.

5. (Previously Presented) A cooling structure of an electronic equipment according to Claim 1, wherein said air openings are adjusted by reducing or enlarging a size of said air openings, or decreasing or increasing the number of said air openings in said opening areas.

6. (Original) A cooling structure of an electronic equipment according to Claim 1, further comprising a motor for driving said exhaust means, and control means for controlling a driving input relative to said motor to control the number of revolution.

7. (Previously Presented) A cooling structure of an electronic equipment needing forced-air-cooling comprising:

at least one substrate housing part detachably housing therein one or plurality of substrate units;

an upstream side duct for allowing air for cooling to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling which passed through said substrate housing part in a first direction to flow;

first exhaust means provided at a first exhaust part for allowing said downstream side duct to open to an outside air to forcibly discharge air in said substrate housing part to the outside air, thereby allowing the air for cooling to flow to said substrate housing part;

a housing unit detachably installed in said downstream side duct;

second exhaust means for allowing the air for cooling to flow from said downstream side duct into said housing unit by exhausting air from a second exhaust part for allowing said housing unit to open to the outside air; and

air adjusting means installed in either or both of boundary parts where said substrate housing part contacts said downstream side duct or said upstream side duct, said air adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part,

wherein a volume of the air for cooling is adjusted by dividing between air leading to said first exhaust means through said downstream side duct and air leading to said second exhaust means through said housing unit, by said housing unit installed in said downstream side duct,

thereby adjusting the air for cooling to a volume of air corresponding to said substrate units installed in said substrate housing part.

8. (Original) A cooling structure of an electronic equipment according to Claim 7, wherein said second exhaust part of said housing unit side and said downstream side duct are partitioned to have an exhaust guide for intercepting exhaust air at said housing unit side from said downstream side duct.

9. (Previously Presented) A cooling structure of an electronic equipment needing forced-air-cooling comprising:

at least one substrate housing part installed in a housing to detachably house therein substrate units;

an upstream side duct provided at the upstream side of air for cooling which is allowed to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling, which passed through said substrate housing part from said upstream side duct, to flow;

an intake part for guiding the air for cooling to said upstream side duct;

an exhaust part for exhausting the air for cooling from said downstream side duct;

exhaust means installed in said exhaust part for forcibly discharging air in said housing to an outside air to allow the air for cooling to flow to said substrate housing part; and

air adjusting means for adjusting the air for cooling which flows from said upstream side duct to said downstream side duct through said substrate housing part, said air adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part,

wherein said air adjusting means is installed in either or both of a first boundary part where said substrate housing part and said downstream side duct contact each other or a second boundary part where said substrate housing part and said upstream side duct contact each other, thereby adjusting the air for cooling to a volume of air corresponding to said substrate units installed in said substrate housing part.

10. (Previously Presented) A cooling structure of an electronic equipment according to Claim 9, further comprising a housing unit provided in said downstream side duct with an intake part which is allowed to open to said downstream side duct, and intake fans installed at said intake part.

11. (Previously Presented) A cooling structure of an electronic equipment needing forced-air-cooling comprising:

at least one substrate housing part for detachably housing therein substrate units from a wall face side of a housing;

an upstream side duct provided at the upstream side of air for cooling which is allowed to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling, which passed through said substrate housing part from said upstream side duct, to flow;

a ventilation part provided at the wall face of said housing for allowing said upstream side duct to open to an outside air;

a first exhaust part provided at the wall face of said housing for allowing said downstream side duct to open to the outside air;

first exhaust means provided at said first exhaust part to forcibly discharge air in said housing to the outside air to allow the air for cooling to flow to said substrate housing part;

air adjusting means for adjusting the air for cooling which flows from said upstream side duct to said downstream side duct through said substrate housing part, said air

adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part; and

a housing unit installed on said downstream side duct for housing a circuit unit;
and

second exhaust means provided in said housing unit or housing for exhausting air from said second exhaust part of said housing by allowing the air for cooling to flow to said housing unit,

wherein said air adjusting means is installed in either or both of a first boundary part where said substrate housing part and said downstream side duct contact each other or a second boundary part where said substrate housing part and said upstream side duct contact each other, the air for cooling is adjusted to a volume of air corresponding to said substrate units installed in said substrate housing part by said air adjusting means, and a volume of the air for cooling which flows to said downstream side duct is adjusted by said housing unit.

12. (Previously Presented) An information processing equipment comprising:

at least one substrate housing part detachably housing therein one or plurality of substrate units;

an upstream side duct provided at the upstream side of air for cooling which is allowed to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling which passed from said upstream side duct through said substrate housing part to flow;

exhaust means provided at an exhaust part for allowing said downstream side duct to open to an outside air to forcibly discharge air in said substrate housing part to the outside air, thereby allowing the air for cooling to flow to said substrate housing part; and

air adjusting means for adjusting the air for cooling which passes from said upstream side duct to said downstream side duct through said substrate housing part, said air adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part,

wherein said air adjusting means is installed in either or both of a first boundary part where said substrate housing part and said downstream side duct contact each other or a second boundary part where said substrate housing part and said upstream side duct contact each other, thereby adjusting the air for cooling to a volume of air corresponding to said substrate units installed in said substrate housing part.

13. (Previously Presented) An information processing equipment according to Claim 12, wherein said air adjusting means adjusts a volume of entire air for cooling which flows to said substrate housing part.

14. (Original) An information processing equipment according to Claim 12, wherein said air adjusting means changes exhaust capacity of the exhaust means.

15. (Previously Presented) An information processing equipment according to Claim 12, further comprising first and second substrate housing frame bodies which are detachably provided in a housing, and said substrate housing part is installed in each of said substrate housing frame bodies.

16. (Previously Presented) An information processing equipment according to Claim 12, wherein said air openings are adjusted by reducing or enlarging a size of the air openings, or decreasing or increasing the number of said air openings in said opening areas.

17. (Original) An information processing equipment according to Claim 12, further comprising a motor for driving said exhaust means, and control means for controlling a driving input relative to said motor to control the number of revolution.

18. (Currently Amended) An information processing equipment comprising:

at least one substrate housing part detachably housing therein one or plurality of substrate units;

an upstream side duct for allowing air for cooling to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling which passed through said substrate housing part to flow;

first exhaust means provided at a first exhaust part for allowing said downstream side duct to open to an outside air to forcibly discharge air in said substrate housing part to the outside air, thereby allowing the air for cooling to flow to said substrate housing part;

a housing unit detachably installed in said downstream side duct;

second exhaust means for allowing the air for cooling to flow from said downstream side duct into said housing unit by exhausting air from a second exhaust part for allowing said housing unit to open to the outside air; and

air adjusting means installed in either or both of boundary parts where said substrate housing part contacts said downstream side duct or said upstream side duct, said air adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part,

wherein a volume of the air for cooling is adjusted by dividing between air leading to said first exhaust means through said downstream side duct and air leading to said second exhaust means through said housing unit, by said housing unit installed in said downstream side duct,

thereby adjusting the air for cooling to a volume of air corresponding to said substrate units installed in said substrate housing part.

19. (Original) An information processing equipment according to Claim 18, wherein said second exhaust part of said housing unit side and said downstream side duct are partitioned to have an exhaust guide for intercepting exhaust air at said housing unit side from said downstream side duct.

20. (Previously Presented) An information processing equipment comprising:

at least one substrate housing part installed in a housing to detachably house therein substrate units;

an upstream side duct provided at the upstream side of air for cooling which is allowed to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling, which passed through said substrate housing part from said upstream side duct, to flow;

an intake part for guiding the air for cooling to said upstream side duct;

an exhaust part for exhausting the air for cooling from said downstream side duct;

exhaust means installed in said exhaust part for forcibly discharging air in said housing to an outside air to allow the air for cooling to flow to said substrate housing part; and

air adjusting means for adjusting the air for cooling which flows from said upstream side duct to said downstream side duct through said substrate housing part, said air

adjusting means having a plurality of adjustable air openings in opening areas corresponding to each of said substrate units in said substrate housing part,

wherein said air adjusting means is installed in either or both of a first boundary part where said substrate housing part and said downstream side duct contact each other or a second boundary part where said substrate housing part and said upstream side duct contact each other, thereby adjusting the air for cooling to a volume of air corresponding to said substrate units installed in said substrate housing part.

21. (Previously Presented) An information processing equipment according to Claim 20, further comprising a housing unit provided in said downstream side duct with an intake part which is allowed to open to said downstream side duct, and intake fans installed at said intake part.

22. (Currently Amended) An information processing equipment comprising:

at least one substrate housing part for detachably housing therein substrate units
from a wall face side of a housing;

an upstream side duct provided at the upstream side of air for cooling which is allowed to flow to said substrate housing part;

a downstream side duct for allowing the air for cooling, which passed through said substrate housing part from said upstream side duct, to flow;

a ventilation part provided at the wall face of said housing for allowing said upstream side duct to open to an outside air;

a first exhaust part provided at the wall face of said housing for allowing said downstream side duct to open to the outside air;

first exhaust means provided at said first exhaust part to forcibly discharge air in said housing to the outside air to allow the air for cooling to flow to said substrate housing part;

air adjusting means for adjusting the air for cooling which flows from said upstream side duct to said downstream side duct through said substrate housing part, said air adjusting means having a plurality of adjustable air openings in opening areas corresponding to said substrate units in said substrate housing part;

a housing unit installed on said downstream side duct for housing a circuit unit;
and

second exhaust means provided in said housing unit or housing for exhausting air from a second exhaust part of said housing by allowing the air for cooling to flow to said housing unit,

wherein said air adjusting means is installed in either or both of a first boundary part where said substrate housing part and said downstream side duct contact each other or a second boundary part where said substrate housing part and said upstream side duct contact each other, the air for cooling is adjusted to a volume of air corresponding to said substrate units installed in said substrate housing part by said air adjusting means, and a

volume of the air for cooling which flows to said downstream side duct is adjusted by said housing unit.